

10 9 8 7 6 5 4 3 2 1

F

F

E

E

D

D

C

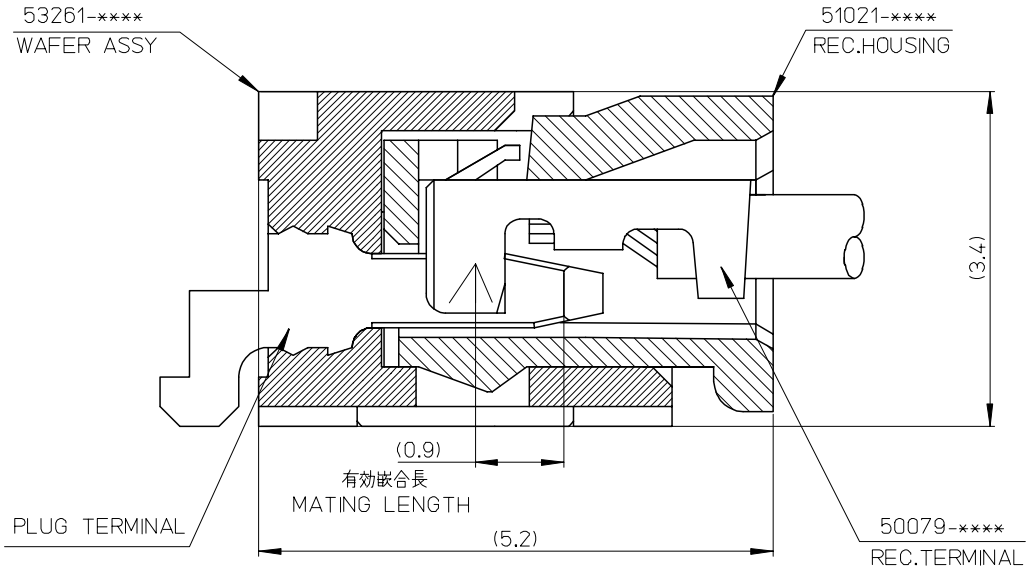
C

B

B

A

A



53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: A0YAGI 2006/02/02 CHKD: YMAEDA 2006/02/03 APPR: NUKITA 2006/02/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY Y. A0YAGI	DATE 2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION			
	10 OVER 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30	MOLEX INCORPORATED			
	30 OVER	± ---	APPROVED BY N. UKITA	DATE 2006/01/30	DOCUMENT NO. SD-51021-002			
	ANGULAR	± --- °	MATERIAL NO. SEE CHART		SHEET NO. 1 OF 1			
0	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

9

8

7

6

5

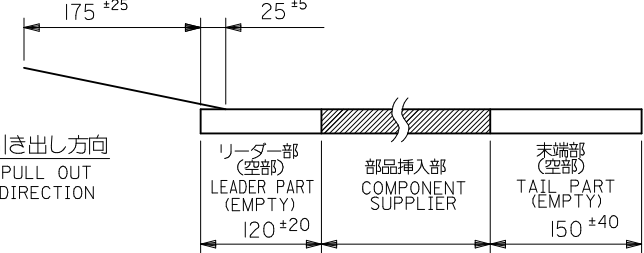
4

3

2

注記
NOTES

- 53261-**-19 の詳細寸法については図面 SD-53261-024 を参照下さい。
RE DETAILED DIMENSIONS, SEE SD-53261-024
- 梱包数量: 1000個/リール
NUMBER OF CONNECTOR: 1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH
トップテープリーダー部 TOP TAPE LEADER PART
トップテープ未接着部 TOP TAPE NON-BONDED PART



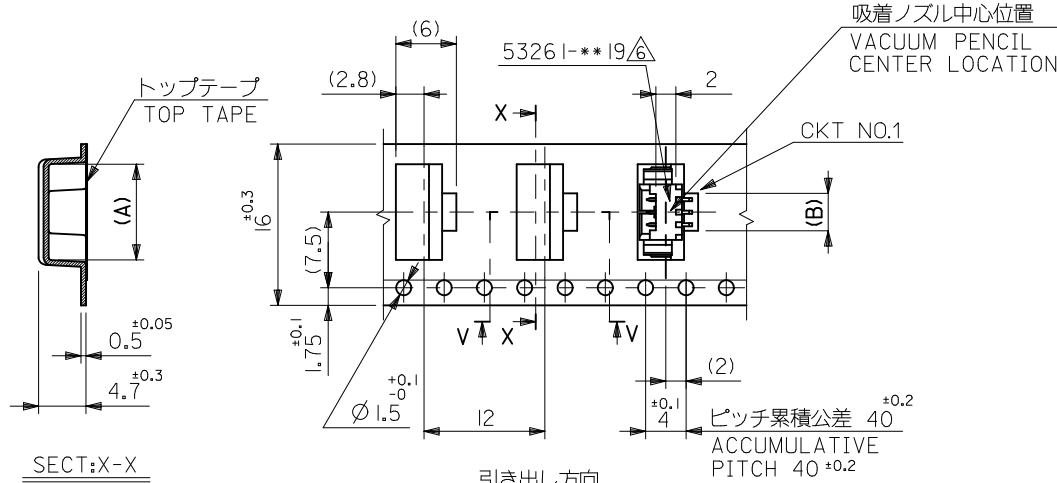
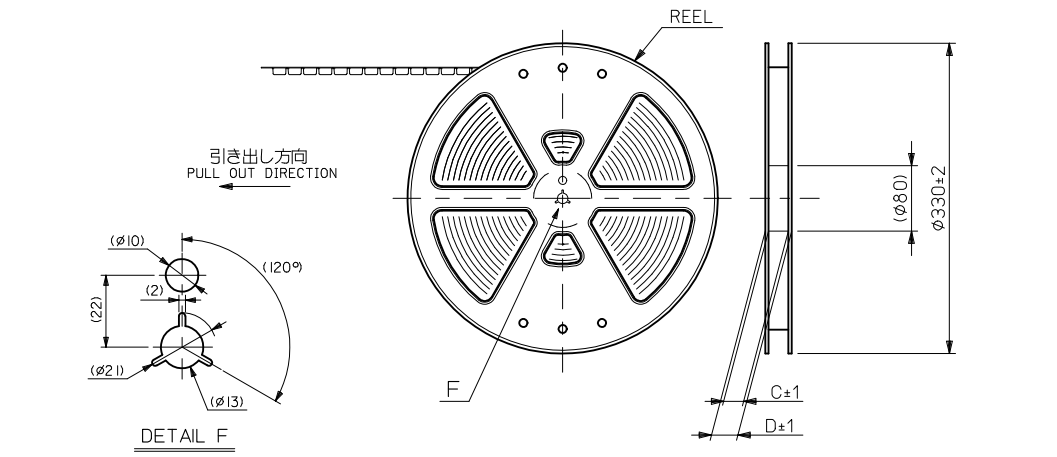
- 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)
トップテープ (TOP TAPE): PET, PE, PEF
リール (REEL): ポリスチレン (PS) <リサイクル材含む>
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>

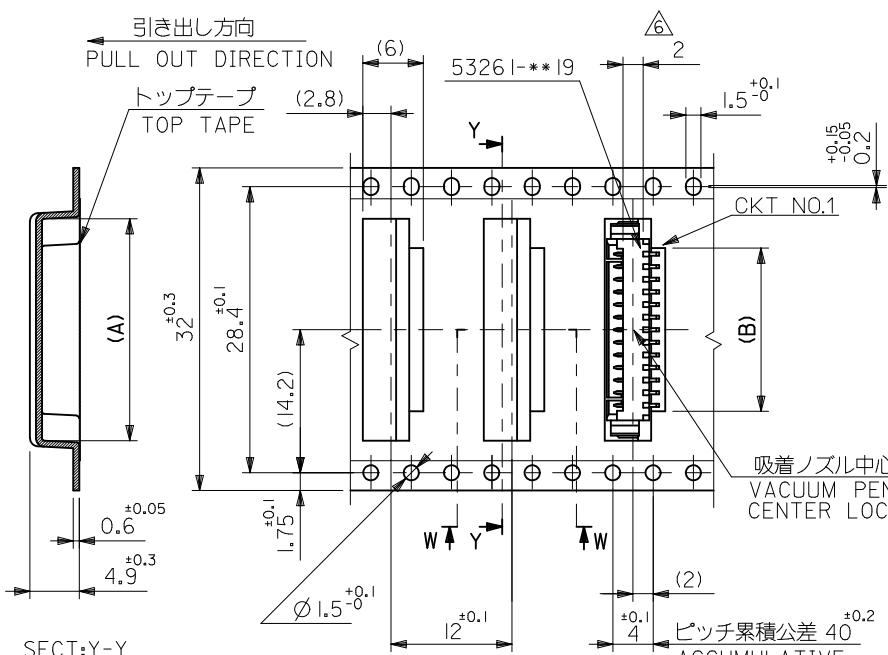
△ コネクタ、ハウジング平面部
CONNECTOR, HOUSING FLAT AREA

- 本製品は 53261-**-90 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53261-**-90
- ELV及びRoHS適合品
ELV AND RoHS COMPLIANT
- 本製品は乾燥剤入り、ハイバリア梱包仕様である。
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

16	21.4	17.4	3.7	9.5	53261-0371	3				
			2.45	8.25	53261-0271	2				
キャリアテープ幅 CARRIER TAPE WIDTH					D	C	B	A	EMBOSSD TAPE PACKAGE オーダー番号 ORDER NO.	極数 CKT.

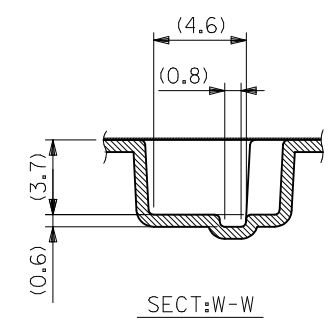
REVISED	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
EC NO: D	2010/02/17 DRWN: YGOTO CHKD: KASAKAWA APPR:	10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3 ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MM ONLY	---	METRIC	☉
			DRAWN BY: H. SHIMABUKUR DATE: '04/02/06 CHECKED BY: K. TOJO DATE: '04/02/06 APPROVED BY: NUKITA DATE: 2010/02/18	TITLE	1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG	
			MATERIAL NO. SEE TABLE & SHEET 2,3	DOCUMENT NO.	MOLEX INCORPORATED SD-53261-023	
			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
						SHEET NO. 1 OF 3



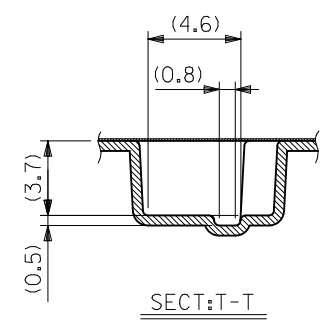


SECT:Y-Y

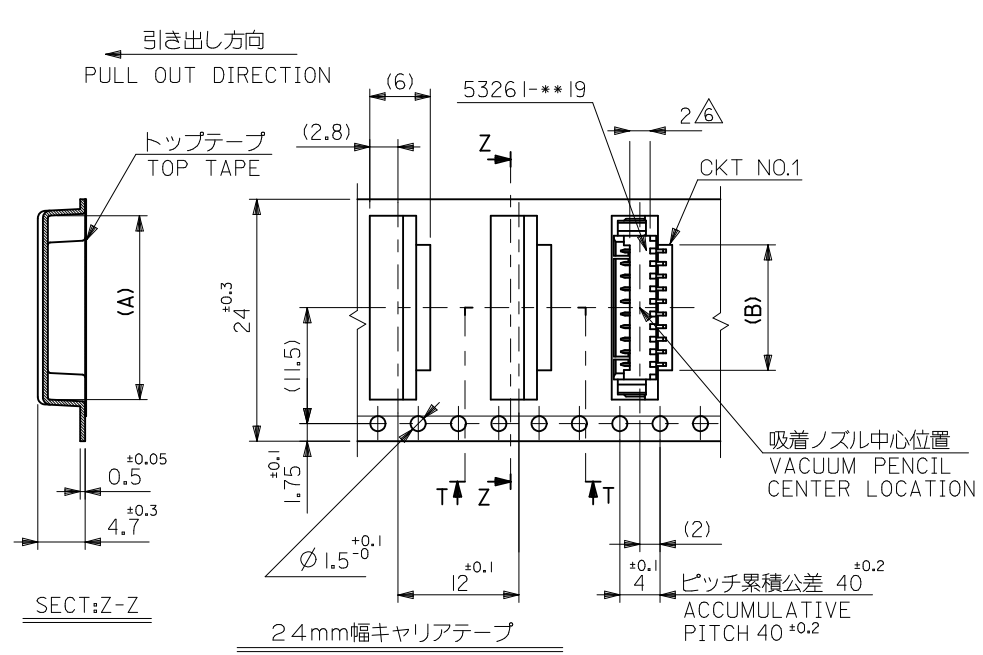
32mm幅キャリアテープ
32mm WIDTH CARRIER TAPE



SECT:W-W



SECT:T-T



SECT:Z-Z

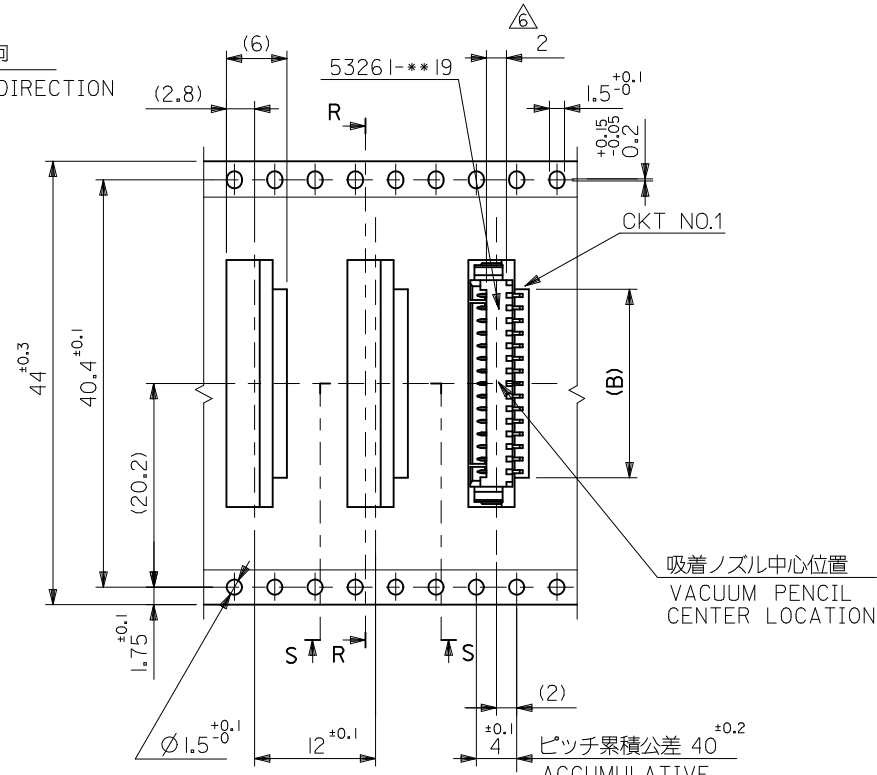
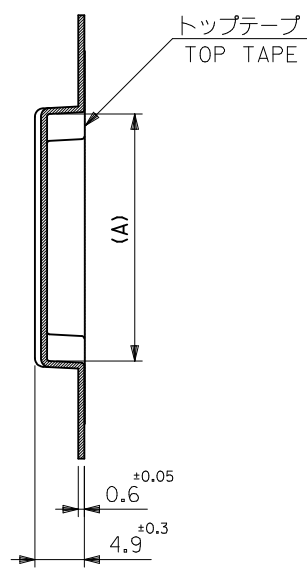
24mm幅キャリアテープ
24mm WIDTH CARRIER TAPE

32	37.4	33.4	16.2	22	53261-1371	13
			14.95	20.75	-1271	12
24	29.4	25.4	13.7	19.5	-1171	11
			12.45	18.25	-1071	10
			11.2	17	-0971	9
			9.95	15.75	-0871	8
			8.7	14.5	-0771	7
			7.45	13.25	-0671	6
			6.2	12	-0571	5
			4.95	10.75	53261-0471	4

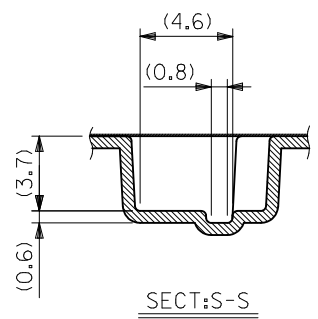
キャリアテープ幅
CARRIER TAPE WIDTH

MODEL NO.	53261-***71	DIMENSION STYLE	MM ONLY	SCALE	---	DESIGN UNITS	METRIC	THIRD ANGLE PROJECTION	
REVISED	2010/02/17	GENERAL TOLERANCES (UNLESS SPECIFIED)	10 UNDER ±0.2	DRAWN BY	H. SHIMABUKUR	DATE	'04/02/06	TITLE	1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG
EC NO.	D	10 OVER 30 UNDER ±0.25	30 OVER ±0.3	CHECKED BY	K. TOJO	DATE	'04/02/06	DESIGN UNITS	METRIC
DRWN:	YGOTO	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	APPROVED BY	NUKITA	DATE	2010/02/18	MOLEX INCORPORATED	
CHKD:	KASAKAWA			MATERIAL NO.		SEE TABLE & SHEET 1.3		DOCUMENT NO.	SD-53261-023
APPR:				SIZE	A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		SHEET NO.	2 OF 3

引き出し方向
PULL OUT DIRECTION

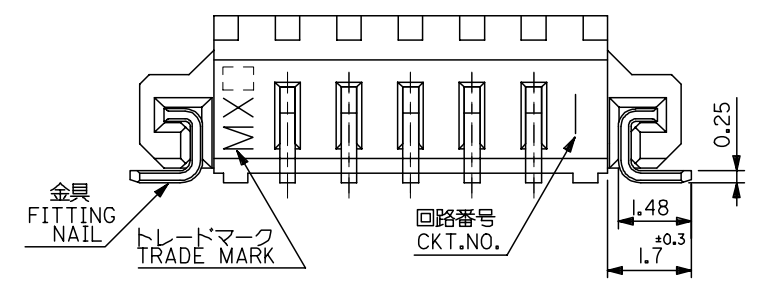
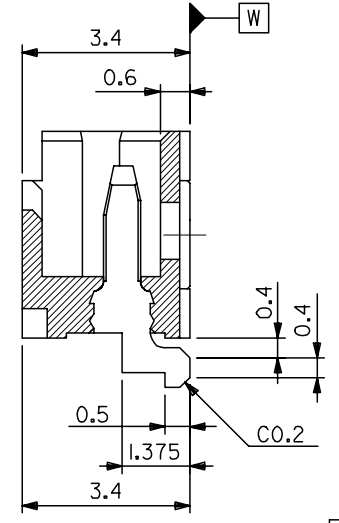
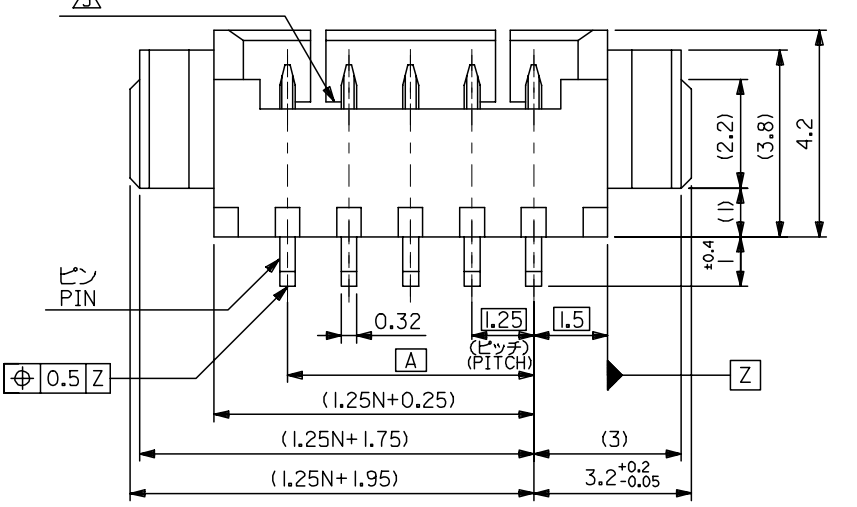
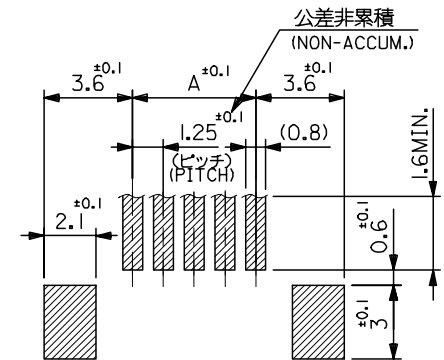
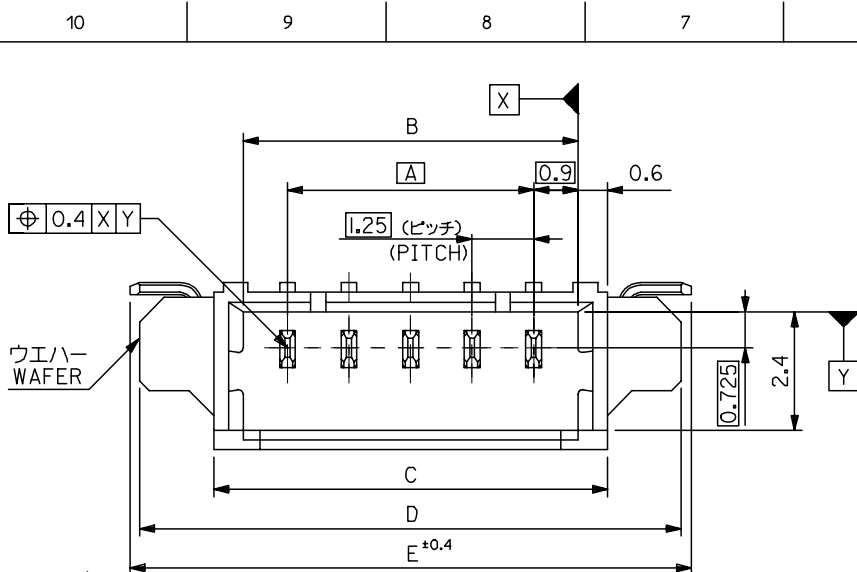


44mm幅キャリアテープ
44mm WIDTH CARRIER TAPE



44	49.4	45.4	18.7	24.5	53261-1571	15				
			17.45	23.25	53261-1471	14				
キャリアテープ幅 CARRIER TAPE WIDTH					D	C	B	A	EMBOSSD TAPE PACKAGE	極数 CKT.
MODEL NO. 53261-***71					ORDER NO.		ORDER NO.			

REVISED EC NO: D DRWN:YGOTO CHKD:KASAKAWA APPR: REV	2010/02/17	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	DESCRIPTION	10 UNDER	±0.2	DRAWN BY H. SHIMABUKUR	DATE '04/02/06	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG			
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE '04/02/06				
		30 OVER	±0.3	APPROVED BY NUKITA	DATE 2010/02/18	MOLEX INCORPORATED			
		ANGULAR	±3 °	MATERIAL NO.	SEE TABLE & SHEET 12	DOCUMENT NO.	SD-53261-023		SHEET NO. 3 OF 3
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



- 注記 NOTES**
1. 嵌合相手: 51021 シリウス
MATES WITH: 51021 SERIES
 2. 材質 MATERIAL
ウエハー: NYLON46, UL94V-0
ピン: リン青銅
PIN: PHOS-BRO
: 銅メッキ 1. 0マイクromメートル以上
: TIN 1.0 MICROMETER MINIMUM
: ニッケル下地 1. 0マイクromメートル以上
: NICKEL(UNDER PLATING)1.0 MICROMETER MINIMUM
金具
FITTING NAIL: リン青銅
: PHOS-BRO
: 銅メッキ 1. 0マイクromメートル以上
: TIN 1.0 MICROMETER MINIMUM
: ニッケル下地 1. 0マイクromメートル以上
: NICKEL(UNDER PLATING)1.0 MICROMETER MINIMUM
 - △ ロック窓は2, 3極は1箇所, 4極以上は2箇所とする。
LOCKING WINDOW:
ONE PLACE FOR 2 AND 3 CKT. AND
TWO PLACES FOR MORE THAN 3 CKT.
 4. ソルダータール部のスレ量及び金具(補強板)のスレ量は基準面[W]に対し、上方向0.05 MAX.、下方向に0.1 MAX.とする。[W] OFFSET BETWEEN BASIS PLANE TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM:
UPPER SIDE: 0.05MAX.
LOWER SIDE: 0.1MAX.
 5. 本製品は 53261-**-10 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53261-**-10

26.4	26	23	21.8	20	53261-1719	17	
23.9	23.5	20.5	19.3	17.5	-1519	15	
22.65	22.25	19.25	18.05	16.25	-1419	14	
21.4	21	18	16.8	15	-1319	13	
20.15	19.75	16.75	15.55	13.75	-1219	12	
18.9	18.5	15.5	14.3	12.5	-1119	11	
17.65	17.25	14.25	13.05	11.25	-1019	10	
16.4	16	13	11.8	10	-0919	9	
15.15	14.75	11.75	10.55	8.75	-0819	8	
13.9	13.5	10.5	9.3	7.5	-0719	7	
12.65	12.25	9.25	8.05	6.25	-0619	6	
11.4	11	8	6.8	5	-0519	5	
10.15	9.75	6.75	5.55	3.75	-0419	4	
8.9	8.5	5.5	4.3	2.5	-0319	3	
53261-**-19	7.65	7.25	4.25	3.05	1.25	53261-0219	2

REVISED EC NO: J2005-3130 DRW:NAIDA 2005/04/19 CHK:KTOYODA 2005/04/21 APPR:NUKITA 2005/04/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY HSHIMABU	DATE 04/02/06	TITLE 1.25 WIRE TO BOARD WAFER ASS FOR SMT -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE 04/02/06	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY MSASAO	DATE 04/02/06	DOCUMENT NO. SD-53261-024		
	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE DRAWING		SHEET NO. 1 OF 1	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							